



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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DSK9J01×0L

Silicon N-channel Junction FET

For low frequency amplification / For piezoelectric sensor
 DSK5J01 in SSMINI3 type package

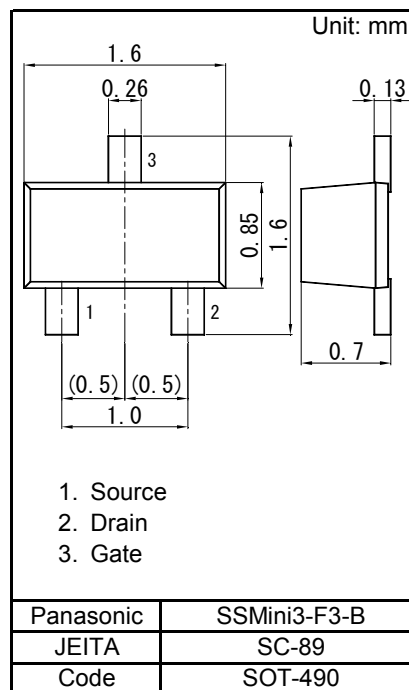
■ Features

- High gate-drain Voltage(Source open)VGDO
- Halogen-free / RoHS compliant
 (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol: B6

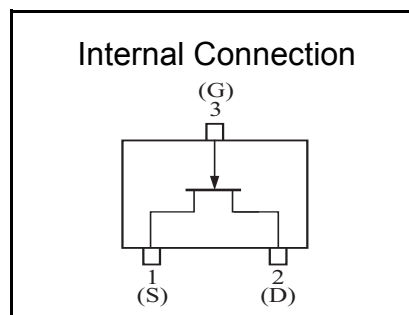
■ Packaging

Embossed type (Thermo-compression sealing) : 3 000 pcs / reel (standard)



■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Gate-drain voltage (Source short)	VGDS	-55	V
Drain current	ID	30	mA
Gate current	IG	10	mA
Power dissipation	PD	125	mW
Channel temperature	Tch	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C



■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Gate-drain voltage (Source short)	VGDS	IG = -100 μA, VDS = 0	-55			V
Drain current *1	IDSS	VDS = 10 V, VGS = 0	1.0		6.5	mA
Gate-source cutoff current	IGSS	VGS = -30 V, VDS = 0			-10	nA
Gate-source cutoff voltage	VGSC	VDS = 10 V, ID = 10 μA			-5	V
Forward transfer admittance	Yfs	VDS = 10 V, ID = 5 mA, f = 1 kHz	2.5	7.5		mS
Small-signal short-circuit input capacitance	Ciss	VDS = 10 V, VGS = 0, f = 1 MHz		6.0		pF
Small-signal reverse transfer capacitance	Crss			2.5		pF

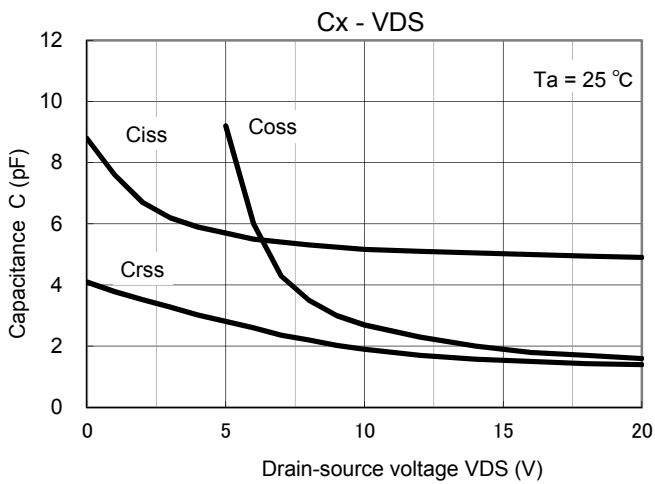
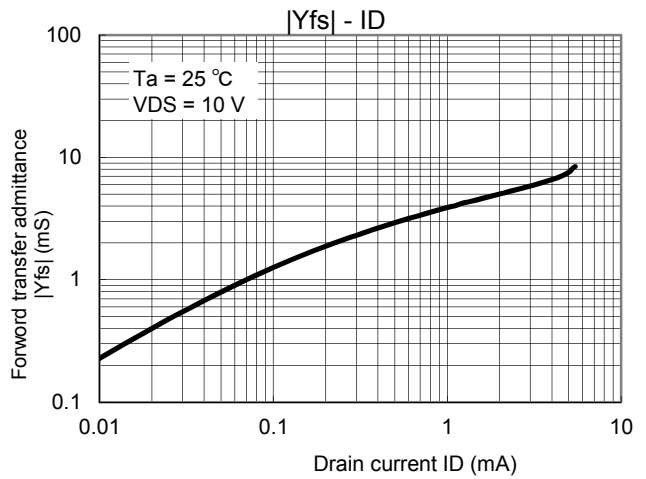
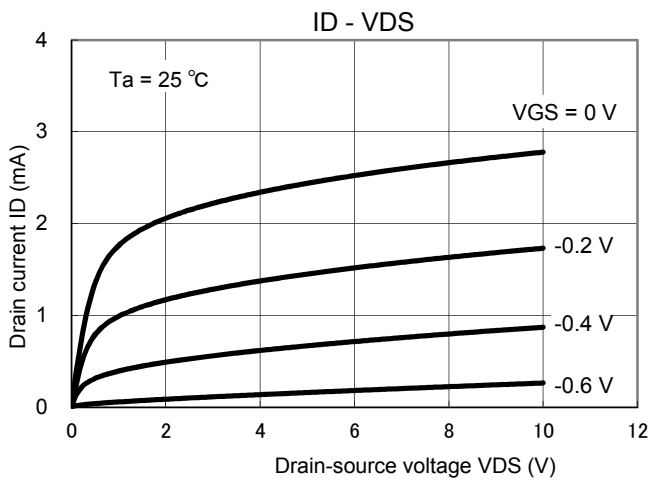
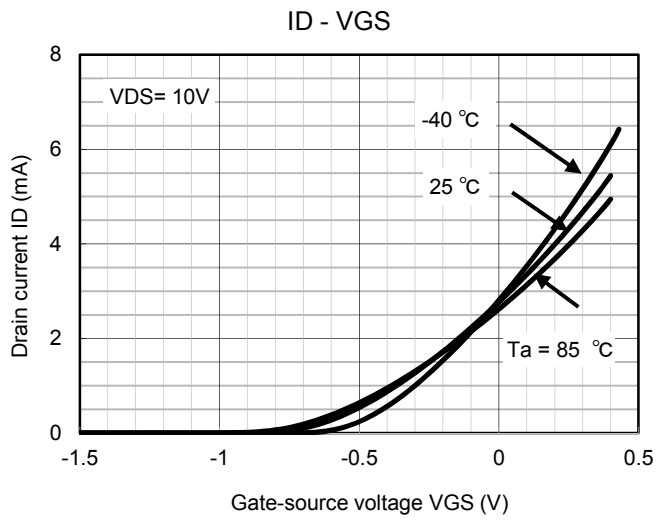
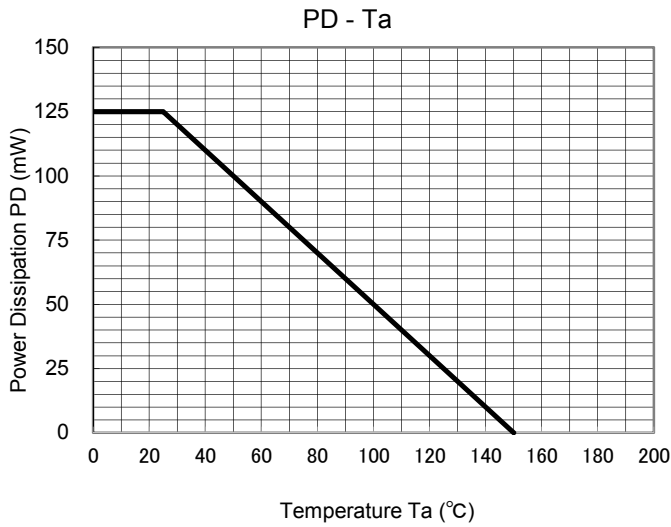
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

*1 Rank classification

Code	P	Q
Rank	P	Q
IDSS (mA)	1.0 to 3.0	2.0 to 6.5
Marking symbol	B6P	B6Q



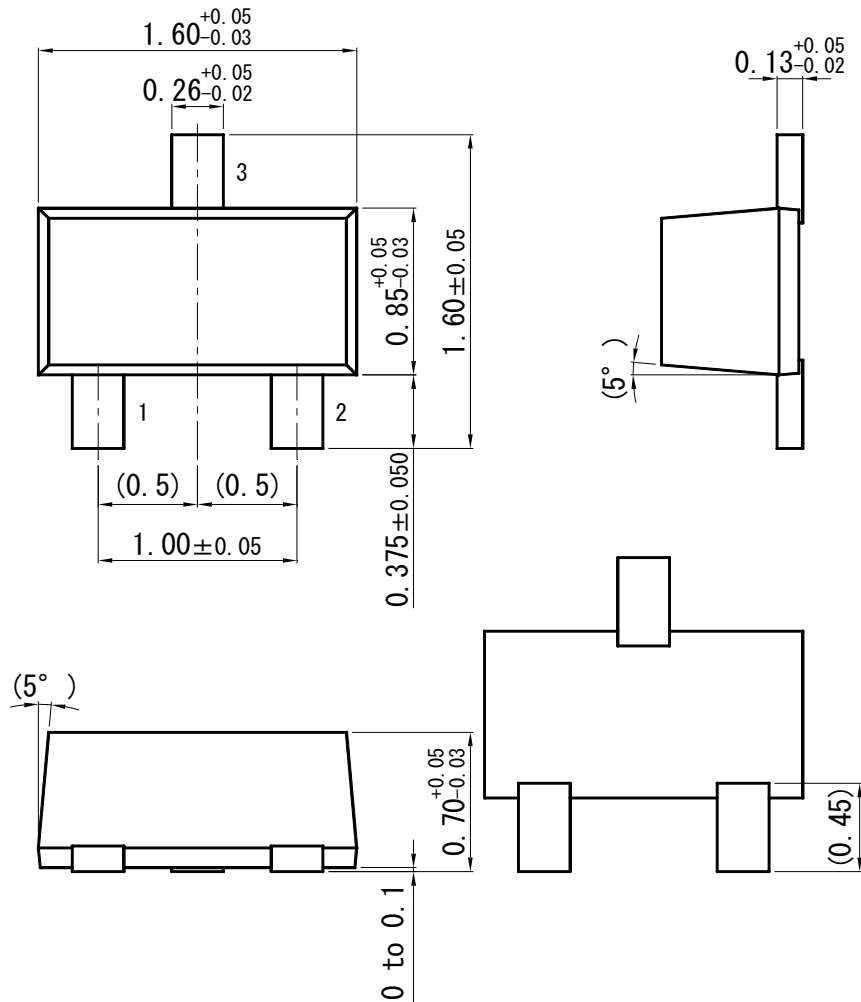
Technical Data (reference)



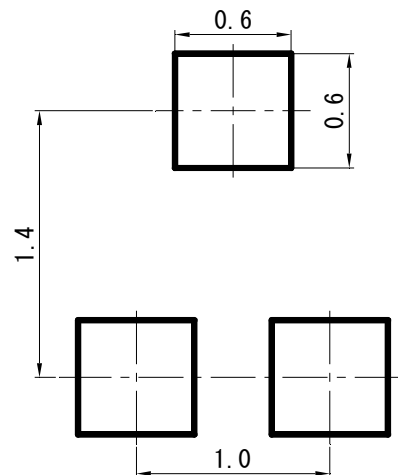
Panasonic

SSMini3-F3-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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